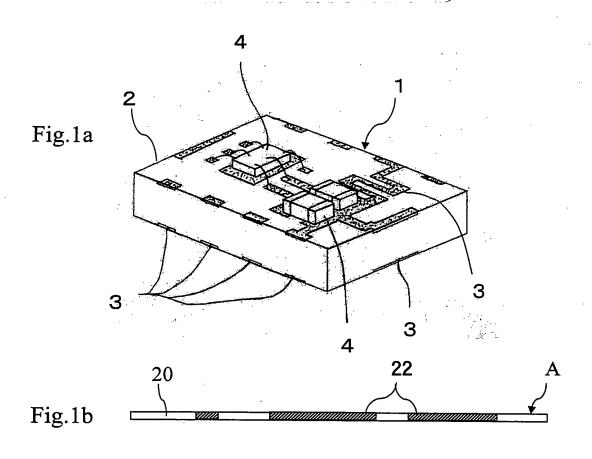
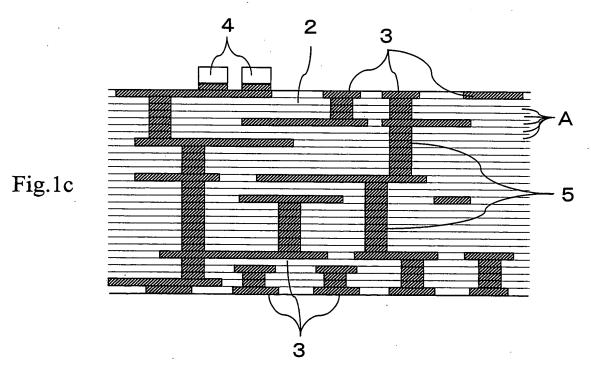
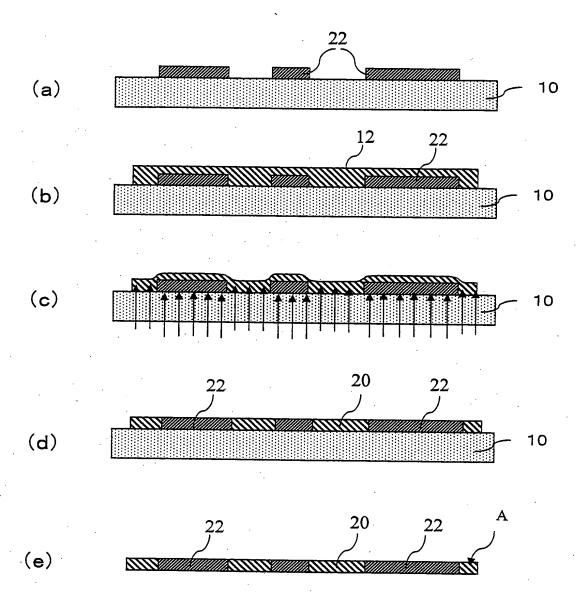
HOGAN & HARTSON -81707.0190 FAKAMI, et al., "Circuit-Parts Sheet and Method of Producing a Multi-Layer Circuit Board" EV 324 111 110 US Page 1 of 9





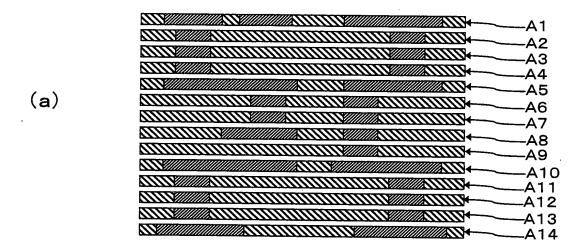
BEST AVAILABLE COPY

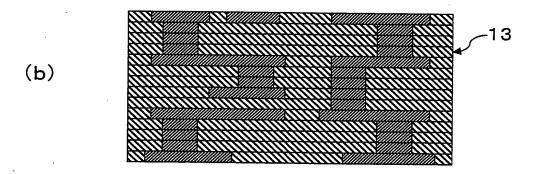
Fig.2



HOGAN & HARTSON -81707.0190 FAKAMI, et al., "Circuit-Parts Sheet and Method of Producing a Multi-Layer Circuit Board" EV 324 111 110 US Page 3 of 9

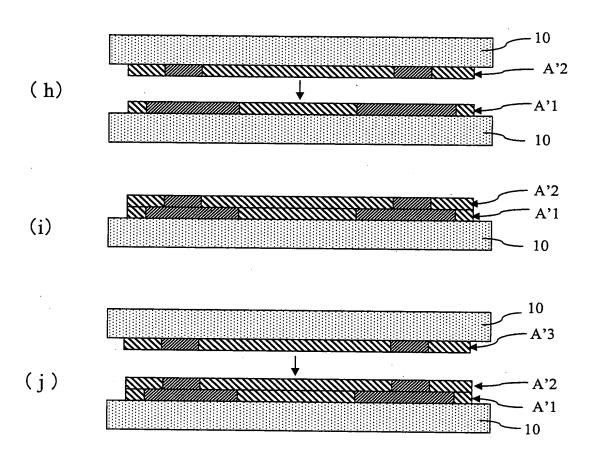
Fig.3

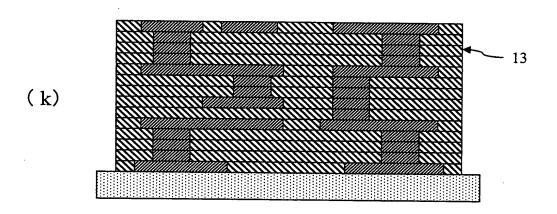




HOGAN & HARTSON -81707.0190 FAKAMI, et al., "Circuit-Parts Sheet and Method of Producing a Multi-Layer Circuit Board" EV 324 111 110 US Page 4 of 9

Fig.4





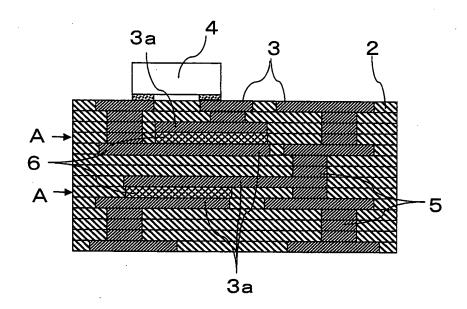
HOGAN & HARTSON -81707.0190

FAKAMI, et al., "Circuit-Parts Sheet and Method of Producing a Multi-Layer Circuit Board"

EV 324 111 110 US

Page 5 of 9

Fig. 5



HOGAN & HARTSON -81707.0190
FAKAMI, et al., "Circuit-Parts Sheet and Method of Producing a Multi-Layer Circuit Board"
EV 324 111 110 US
Page 6 of 9

Fig. 6

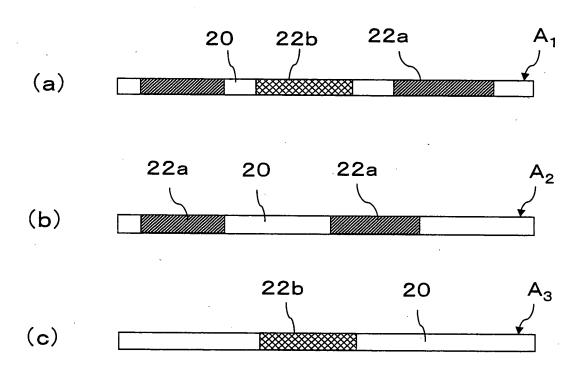


Fig. 7

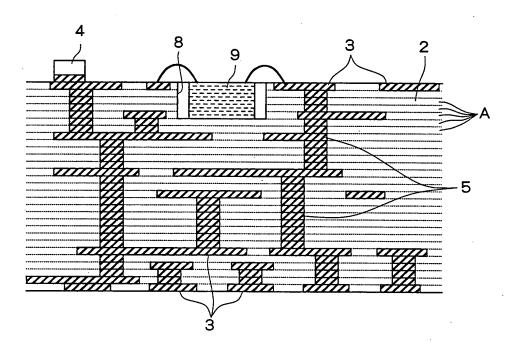
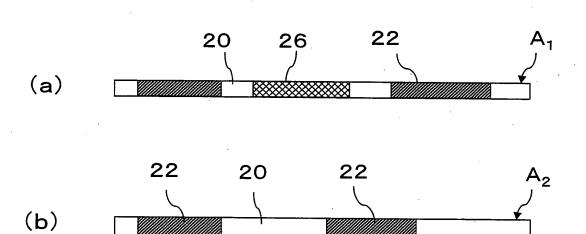


Fig. 8



HOGAN & HARTSON –817,07.0190
FAKAMI, et al., "Circuit-Parts Sheet and Method of Producing a Multi-Layer Circuit Board"
EV 324 111 110 US
Page 9 of 9

Fig. 9

